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May 2015

### FDS86267P

### P-Channel Shielded Gate PowerTrench® MOSFET

-150 V, -2.2 A, 255 mΩ

#### **Features**

- Shielded Gate MOSFET Technology
- Max  $r_{DS(on)}$  = 255 m $\Omega$  at  $V_{GS}$  = -10 V,  $I_D$  = -2.2 A
- Max  $r_{DS(on)}$  = 290 m $\Omega$  at  $V_{GS}$  = -6 V,  $I_D$  = -2 A
- Very Low r<sub>DS(on)</sub> Mid Voltage P-channel Silicon Technology Optimised for Low Qg
- This Product is Optimised for Fast Switching Applications as well as Load Switch Applications
- 100% UIL Tested
- RoHS Compliant

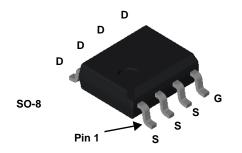


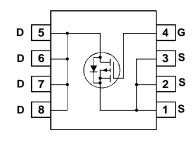
#### **General Description**

This P-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates shielded gate technology. The process has been optimized for the on-state resistance and yet maintain superior switching performance.

### **Applications**

- Active Clamp Switch
- Load Switch





#### **MOSFET Maximum Ratings** T<sub>A</sub> = 25 °C unless otherwise noted.

Symbol	Parameter			Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage			-150	V
V <sub>GS</sub>	Gate to Source Voltage			±25	V
	Drain Current -Continuous		(Note 1a)	-2.2	^
'D	-Pulsed		(Note 4)	-34	A
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	54	mJ
В	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	2.5	W
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1b)	1.0	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Ra	nge		-55 to +150	°C

#### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	125	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS86267P	FDS86267P	SO-8	13 "	12 mm	2500 units

### **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	cteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-150			V
$\Delta BV_{DSS} \over \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25 °C		-121		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -120 V, V <sub>GS</sub> = 0 V			-1	μА
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-2	-3	-4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25 °C		5		mV/°C
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = -10 V, I <sub>D</sub> = -2.2 A		191	255	
		$V_{GS} = -6 \text{ V, } I_D = -2 \text{ A}$		214	290	mΩ
		$V_{GS} = -10 \text{ V}, I_D = -2.2 \text{ A}, T_J = 125 \text{ °C}$		342	448	1
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -2.2 A		6.8		S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -75 V, V <sub>GS</sub> = 0 V, f = 1 MHz		806	1130	pF
Coss	Output Capacitance			54	75	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			1.6	2.3	pF
R <sub>q</sub>	Gate Resistance		0.1	3	6	Ω

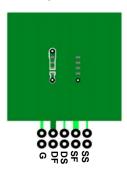
#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		9.7	20	ns
t <sub>r</sub>	Rise Time	V <sub>DD</sub> = -75 V, I <sub>D</sub> = -2.2 A,	2.5	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS}$ = -10 V, $R_{GEN}$ = 6 $\Omega$	17	30	ns
t <sub>f</sub>	Fall Time		5.7	12	ns
$Q_g$	Total Gate Charge	V <sub>GS</sub> = 0 V to -10 V	11	16	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0 \text{ V to -6 V} V_{DD} = -75 \text{ V},$	7	10	nC
$Q_{gs}$	Gate to Source Charge	I <sub>D</sub> = -2.2 A	3.2		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		1.9		nC

#### **Drain-Source Diode Characteristics**

V <sub>SD</sub> Source	Source-Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = -2.2 A (Note 2)	-0.8	-1.3	V
		$V_{GS} = 0 \text{ V, } I_{S} = -2 \text{ A}$ (Note 2)	-0.8	-1.2	
t <sub>rr</sub>	Reverse Recovery Time	1 2 2 A di/dt 100 A/	65	104	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$I_F = -2.2 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s}$	157	251	nC

<sup>1.</sup> R<sub>0JA</sub> is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R<sub>0JC</sub> is guaranteed by design while R<sub>0CA</sub> is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

- 2. Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0%. 3. Starting T $_J$  = 25 °C, L = 3 mH, I $_{AS}$  = -6 A, V $_{DD}$  = -150 V, V $_{GS}$  = -10 V. 100% tested at L = 0.3 mH, I $_{AS}$  = -13 A.
- 4. Pulsed Id please refer to Fig 11 SOA graph for more details.

#### Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

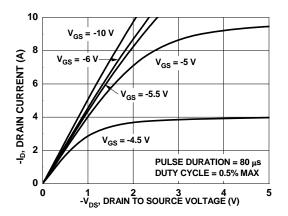


Figure 1. On Region Characteristics

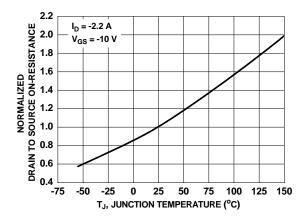


Figure 3. Normalized On Resistance vs Junction Temperature

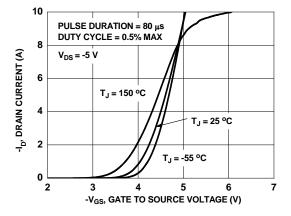


Figure 5. Transfer Characteristics

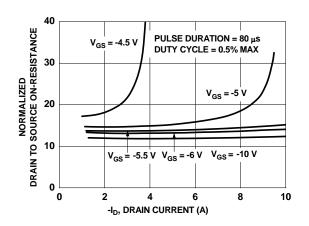


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

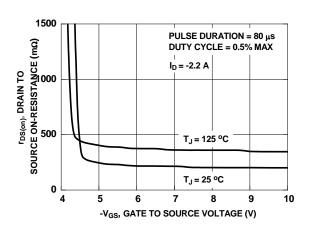


Figure 4. On-Resistance vs Gate to Source Voltage

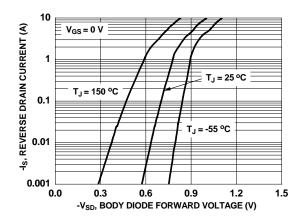


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

### **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

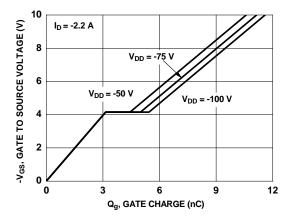


Figure 7. Gate Charge Characteristics

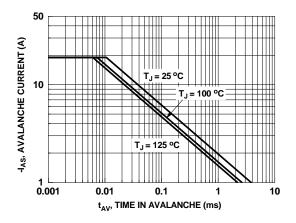


Figure 9. Unclamped Inductive Switching Capability

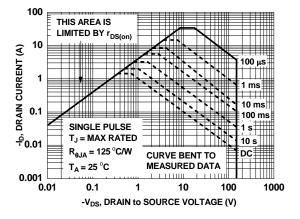


Figure 11. Forward Bias Safe Operating Area

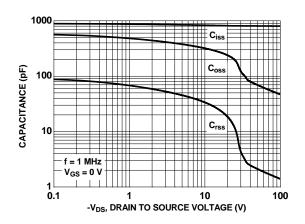


Figure 8. Capacitance vs Drain to Source Voltage

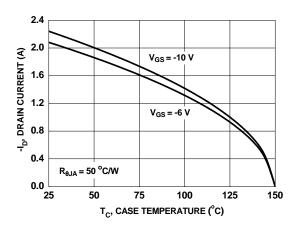


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

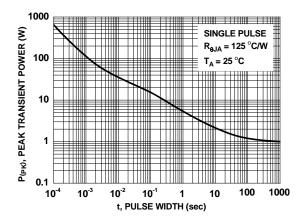


Figure 12. Single Pulse Maximum Power Dissipation



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